**IN THE CLAIMS:**

1. (Currently Amended) A metal base circuit substrate for an optical device comprising a metal base substrate made from aluminum or aluminum alloy that supports an electric circuit via an insulation layer, wherein said insulation layer is formed from a transparent cross-linked silicone body having a light transmission of not less than 80%, and said electric circuit is formed directly on said insulation layer.

2. (Original) The metal base circuit substrate for an optical device according to Claim 1, wherein said insulation layer has a thickness not exceeding 10 μm.

3. (Original) The metal base circuit substrate for an optical device according to Claim 1, wherein a dielectric constant of said cross-linked silicone body does not exceed 4.0.

4. (Original) The metal base circuit substrate for an optical device according to Claim 1, wherein said circuit is formed either by etching a conductive layer formed in said insulation layer by electrolytic or non-electrolytic plating, or by printing said circuit on said insulation layer with the use of an electroconductive ink.

5. (Currently Amended) A method of manufacturing a metal base circuit substrate for an optical device comprising the steps of:

a) applying a cross-linkable silicone onto the surface of a metal base substrate made from aluminum or aluminum alloy;

b) cross-linking said silicone, thereby forming an insulation layer from ~~the~~a transparent cross-linked silicone body having a light transmission of not less than 80%; and then

c) forming an electric circuit directly on said insulation layer either by (i) forming a conductive layer by electrolytic or non-electrolytic plating with subsequent etching, or (ii) by printing with a conductive ink.

6. (Canceled)

7. (Previously Presented) The metal base circuit substrate for an optical device according to Claim 1, wherein said insulation layer has a light transmission of not less than 90%.

8. (Canceled)

9. (Previously Presented) The method of manufacturing a metal base circuit substrate for an optical device according to Claim 5, wherein the insulation layer has a light transmission of not less than 90%.

Please add the following new claims:

10. (New) The metal base circuit substrate for an optical device according to Claim 1, wherein said insulation layer has a pencil hardness of not less than 2H.

11. (New) The method of manufacturing a metal base circuit substrate for an optical device according to Claim 5, wherein said insulation layer has a pencil hardness of not less than 2H.

12. (New) The metal base circuit substrate for an optical device according to Claim 1, wherein said insulation layer has a dielectric constant of not more than 4.

13. (New) The method of manufacturing a metal base circuit substrate for an optical device according to Claim 5, wherein said insulation layer has a dielectric constant of not more than 4.